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50-348/364-CIVP  
5/18/92

STAFF EXH. #68

MEMORANDUM

To: File

92 JUL -2 AM 102

From: J. A. Murphy

Subj: ANO Tape Splice Test, Information Received from Okonite Regarding Thermal Properties of Okonite T-95 Splicing Tape

Date June 19, 1990

At 1600 MLEA (J. A. Murphy & C. J. Crane) called Okonite (Tim Fitzgerald) to determine if he had any further information on the thermal aging problem described to him this morning. He stated that he had a partial answer and provide the following information:

\*T-95 splice tape is an uncured material (i.e. no peroxide was added to the compound).

\*T-95 splice tape will melt at 150 °C because it is uncured.

\*In the NQRN-3 test, the T-95 splice tape was over and in line splice and was completely encapsulated by the No. 35 jacketing tape.

\*Okonite has been telling utilities for years that T-95 splice tape should not be used for bolted V splices without a No. 35 jacket.

\*The Okonite laboratory told him it was not necessary to put a roll of T-95 tape in the thermal aging oven because it would definitely melt.

MLEA asked him if there was a known maximum temperature at which the T-95 tape would not melt. He stated that he would check with the engineer who was involved with all of the T-95 testing and let us know tomorrow morning. He was asked if he would confirm what he had told us in a letter (including the maximum temperature at which melting would not occur. He stated that he would do that by explaining in detail what the NQRN-3 testing means.

cc:

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